Claims

1. An adhesive sheet composed of a thermoplastic and optionally one or more resins, wherein
   a) the adhesive system has a softening temperature of greater than 65°C and less than 125°C,
   b) a melt flow index (ISO 1133) of greater than 3 and less than 100 cm^3/10 minutes,
   c) a storage modulus G' at 23°C, as measured by test method A, of greater than 10^7 Pas,
   d) a loss modulus G" at 23°C, as measured by test method A, of greater than 10^6 Pas,
   e) and a crossover, as measured by test method A, of less than 125°C.

2. The adhesive sheet of claim 1, characterized in that the layer thickness is between 10 and 100 µm, with particular preference between 30 and 80 µm.

3. The adhesive sheet of at least one of the preceding claims, characterized in that thermoplastics used are with particular preference copolyamides, polyethyl-vinyl acetates, polyvinyl acetates, polyolefins, polyurethanes, and copolyesters.

4. The adhesive sheet of at least one of the preceding claims, characterized in that reactive resin used comprises epoxy resins, and/or phenolic resins and/or novolak resins.

5. The use of an adhesive sheet of any one of the above claims for bonding chip modules in card bodies.

6. The use of an adhesive sheet of any one of the above claims for bonding polyimide-, polyester or epoxy-based chip modules and on PVC, ABS, PET, PC, PP or PE card bodies.

7. A method for producing a heat-activable adhesive tape, characterized in that an adhesive sheet of claims 1 to 4 is coated onto a release paper or a release film.